PCN Number:	20230905001.1	PCN Date:	September 06, 2023
Title:	Qualification of CDAT as an alternate Assembly site for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	Dec 4, 2023	Sample Requests accepted until:	Oct 5, 2023*

***Sample requests received after Oct 5, 2023 will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of CDAT as an additional Assembly site for set of devices listed below. Construction differences are as follows:

	UTL3	CDAT
Mount Compound	SID#PZ0076	4207123
Bond wire composition, diameter	Au, 0.8 mil	Cu, 0.8 mil

Reason for Change:

Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
UTL1	NSE	THA	Bangkok
CDAT	**CDA**	**CHN**	**Chengdu**

Sample product shipping label (not actual product label)

Product Affected:

TMAG5231A1CQDMRR	TMAG5231B1DQDMRR	TMAG5231C1GQDMRR	TMAG5231H1DQDMRR
TMAG5231A2DQDMRR	TMAG5231C1DQDMRR		

TI Information
Selective Disclosure

Qualification Report

TMAG5231 DMR CDAT
Approve Date 06-June-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TMAG5231A2DQDMRR	Qual Device: TMAG5231C1GQDMRR	Qual Device: TMAG5231H1DQDMRR	Qual Device: TMAG5231A1CQDMRR	Qual Device: TMAG5231B1DQDMRR	Qual Device: TMAG5231C1DQDMRR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	1/77/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	1/77/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	1/77/0	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	1/77/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	1/22/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	1/3/0	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30	1/30/0	1/30/0	1/30/0

- QBS: Qual By Similarity
- Qual Device TMAG5231A2DQDMRR is qualified at MSL1 260C
- Qual Device TMAG5231C1GQDMRR is qualified at MSL1 260C
- Qual Device TMAG5231H1DQDMRR is qualified at MSL1 260C
- Qual Device TMAG5231A1CQDMRR is qualified at MSL1 260C
- Qual Device TMAG5231B1DQDMRR is qualified at MSL1 260C
- Qual Device TMAG5231C1DQDMRR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2111-058

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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